

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|---|---|------------------|
| 13 | 39 | (US-6225206-\$ or US-5143865-\$ or US-5824438-\$ or US-6162660-\$ or US-6294828-\$ or US-6130476-\$ or US-6251766-\$ or US-6337522-\$ or US-3839727-\$ or US-6260264-\$ or US-5956605-\$ or US-6425516-\$ or US-6118179-\$ or US-6168972-\$ or US-6180504-\$ or US-6291270-\$ or US-5989982-\$ or US-5656863-\$ or US-5897337-\$ or US-6410415-\$ or US-6189208-\$ or US-5747101-\$ or US-5329423-\$ or US-4818728-\$ or US-6100114-\$ or US-5704116-\$).did. or (US-5650667-\$ or US-6355507-\$ or US-5933713-\$ or US-5869899-\$ or US-5496775-\$ or US-6288335-\$ or US-5908317-\$ or US-6054772-\$ or US-5824569-\$ or US-6380061-\$ or US-6281591-\$ or US-5554887-\$ or US-5641113-\$).did. | USPAT | 2002/12/28 10:35 |
| 14 | 5748 | (flipchip (flip adj chip)) and (solder adj (bump ball)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 10:40 |
| 15 | 8874 | (substrate ((wiring circuit) adj board)) near3 polyimide | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 10:44 |
| 16 | 384 | ((flipchip (flip adj chip)) and (solder adj (bump ball))) and ((substrate ((wiring circuit) adj board)) near3 polyimide) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 10:43 |
| 17 | 377 | ((flipchip (flip adj chip)) and (solder adj (bump ball))) and ((substrate ((wiring circuit) adj board)) near3 polyimide)) not ((US-6225206-\$ or US-5143865-\$ or US-5824438-\$ or US-6162660-\$ or US-6294828-\$ or US-6130476-\$ or US-6251766-\$ or US-6337522-\$ or US-3839727-\$ or US-6260264-\$ or US-5956605-\$ or US-6425516-\$ or US-6118179-\$ or US-6168972-\$ or US-6180504-\$ or US-6291270-\$ or US-5989982-\$ or US-5656863-\$ or US-5897337-\$ or US-6410415-\$ or US-6189208-\$ or US-5747101-\$ or US-5329423-\$ or US-4818728-\$ or US-6100114-\$ or US-5704116-\$).did. or (US-5650667-\$ or US-6355507-\$ or US-5933713-\$ or US-5869899-\$ or US-5496775-\$ or US-6288335-\$ or US-5908317-\$ or US-6054772-\$ or US-5824569-\$ or US-6380061-\$ or US-6281591-\$ or US-5554887-\$ or US-5641113-\$).did.) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 10:43 |
| 18 | 9469 | (cap cover lid) near3 (polyimide polymer polymeric) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 10:44 |
| 19 | 44445 | (substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:08 |
| 20 | 696 | ((flipchip (flip adj chip)) and (solder adj (bump ball))) and ((substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 10:59 |

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|----|-----|---|---|------------------|
| 21 | 21 | ((cap cover lid) near3 (polyimide polymer polymeric)) and (((flipchip (flip adj chip)) and (solder adj (bump ball)))) and ((substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:06 |
| 22 | 2 | "6392143" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:06 |
| 23 | 115 | "5285352" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:06 |
| 24 | 8 | "6093972" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:06 |
| 25 | 28 | "5724729" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:07 |
| 26 | 93 | "5067007" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:07 |
| 27 | 9 | "5982038" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:07 |
| 28 | 72 | "5311402" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:07 |
| 29 | 315 | "6392143" "5285352" "6093972" "5724729" "5067007" "5982038" "5311402" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:07 |
| 30 | 315 | ("6392143" "5285352" "6093972" "5724729" "5067007" "5982038" "5311402") not ((US-6225206-\$ or US-5143865-\$ or US-5824438-\$ or US-6162660-\$ or US-6294828-\$ or US-6130476-\$ or US-6251766-\$ or US-6337522-\$ or US-3839727-\$ or US-6260264-\$ or US-5956605-\$ or US-6425516-\$ or US-6118179-\$ or US-6168972-\$ or US-6180504-\$ or US-6291270-\$ or US-5989982-\$ or US-5656863-\$ or US-5897337-\$ or US-6410415-\$ or US-6189208-\$ or US-5747101-\$ or US-5329423-\$ or US-4818728-\$ or US-6100114-\$ or US-5704116-\$).did. or (US-5650667-\$ or US-6355507-\$ or US-5933713-\$ or US-5869899-\$ or US-5496775-\$ or US-6288335-\$ or US-5908317-\$ or US-6054772-\$ or US-5824569-\$ or US-6380061-\$ or US-6281591-\$ or US-5554887-\$ or US-5641113-\$).did.) not (((cap cover lid) near3 (polyimide polymer polymeric)) and (((flipchip (flip adj chip)) and (solder adj (bump ball)))) and ((substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:08 |
| 31 | 27 | ("6392143" "5285352" "6093972" "5724729" "5067007" "5982038" "5311402") and (substrate ((wiring circuit) adj board)) near3 (polyimide polymer polymeric) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:47 |
| 32 | 6 | 6093972.URPN. | USPAT | 2002/12/28 12:19 |

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| 33 | 8 | {"5089440" "5218759" "5285352" "5302849" "5371404" "5659203" "5864178" "5900581").PN. | USPAT | 2002/12/28 12:24 |
| 36 | 15 | "6025648" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:43 |
| 37 | 10 | "6239496" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:44 |
| 38 | 11 | "6188127" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:46 |
| 40 | 19 | ("6025648" "6239496" "6188127") and (polyimide polymer polymeric) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 12:47 |
| 39 | 32 | "6025648" "6239496" "6188127" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 13:01 |
| 41 | 13 | ("6025648" "6239496" "6188127") not (("6025648" "6239496" "6188127") and (polyimide polymer polymeric)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2002/12/28 13:01 |